Product data sheet

1. General description

Planar passivated high commutation three quadrant triac in a SOT78D (TO-220AB) internally insulated plastic package intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. This "series CT" triac will commutate the full RMS current at the maximum rated junction temperature ($T_{j(max)}$ = 150 °C) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- · 3Q technology for improved noise immunity
- 2500 V RMS isolation voltage capability
- · High commutation capability with maximum false trigger immunity
- · High immunity to false turn-on by dV/dt
- High junction operating temperature capability
- High voltage capability
- · Less sensitive gate for high noise immunity
- Internally insulated package
- · Internally isolated mounting base
- · Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

3. Applications

- Applications subject to high temperature
- Heating controls
- High power motor control
- · High power switching

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DRM}	repetitive peak off- state voltage		-	-	800	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 100 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3	-	-	20	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 20 \text{ ms}$; Fig. 4; Fig. 5	-	-	200	Α
		full sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 16.7 \text{ ms}$	-	-	220	Α
Tj	junction temperature		-	-	150	°C

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static chara	acteristics		1				
I _{GT} gate	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; <u>Fig. 7</u>		-	-	35	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 7</u>		-	-	35	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u>		-	-	35	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>		-	-	40	mA
V_{T}	on-state voltage	I _T = 24 A; T _j = 25 °C; <u>Fig. 10</u>		-	1.2	1.5	V
Dynamic ch	naracteristics						
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		1250	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 20 A; dV_{com}/dt = 10 V/ μ s; gate open circuit		16	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 20 \text{ A};$ $dV_{com}/dt = 1 \text{ V/}\mu\text{s}; gate open circuit}$		38	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	T2——T1
2	T2	main terminal 2)	G sym051
3	G	gate		Symost
mb	n.c.	mounting base; isolated	<u> </u>	
			TO-220AB (SOT78D)	

6. Ordering information

Table 3. Ordering information

Type number	Package	e				
	Name	Description	Version			
BTA420Y-800CT	TO-220AB	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220	SOT78D			

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	800	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 100 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3	-	20	A
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig. 4; Fig. 5	-	200	A
		full sine wave; T _{j(init)} = 25 °C; t _p = 16.7 ms	-	220	Α
l ² t	I ² t for fusing	t _p = 10 ms; sine-wave pulse	-	200	A²s
dl _T /dt	rate of rise of on-state current	I _G = 70 mA	-	100	A/µs
I _{GM}	peak gate current		-	2	Α
P_{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	150	°C

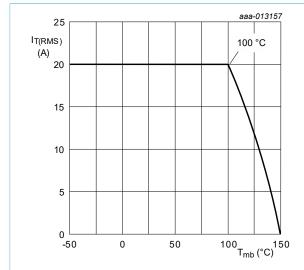


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

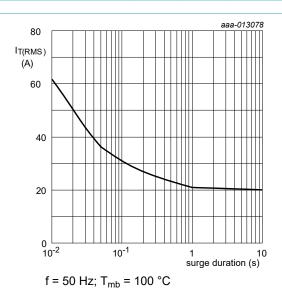


Fig. 2. RMS on-state current as a function of surge duration; maximum values

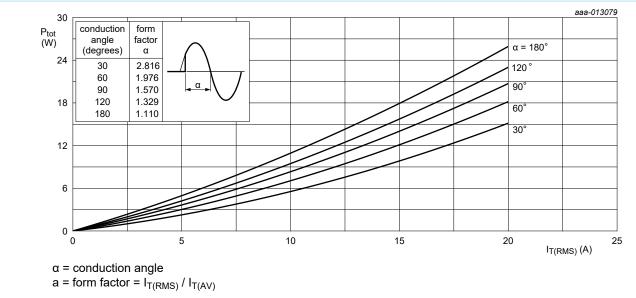


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

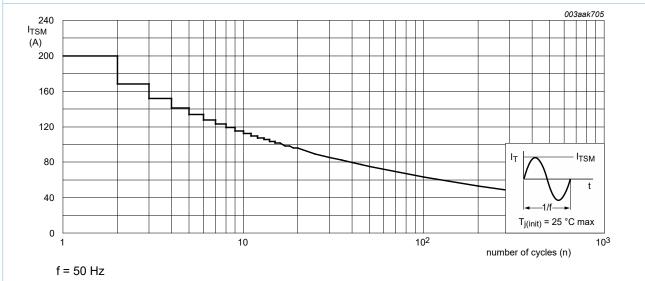
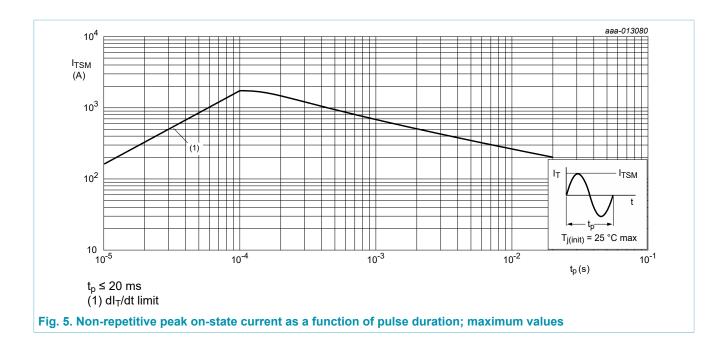


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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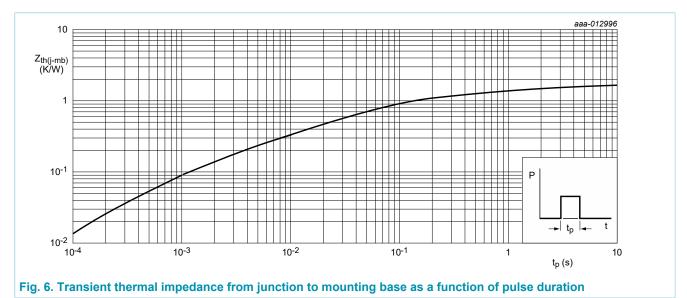


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8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	full cycle; Fig. 6	-	-	1.9	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W



9. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
V _{isol(RMS)}	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; $50~Hz \le f \le 60~Hz$; $RH \le 65~\%$; $T_{mb} = 25~^{\circ}C$		-	-	2500	V	
C _{isol}	isolation capacitance	from main terminal 2 to external heatsink; f = 1 MHz; T _{mb} = 25 °C		-	10	-	pF	

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
Static char	acteristics						
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ \text{ G+;} $ $T_j = 25 \text{ °C; } \frac{\text{Fig. 7}}{}$	-	-	35	mA	
			$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 7}}{}$	-	-	35	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 7}}{}$	-	-	35	mA	
l _L	latching current	$V_D = 12 \text{ V; } I_G = 0.1 \text{ A; } T2 + G+;$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 8}}{}$	-	-	50	mA	
		$V_D = 12 \text{ V; } I_G = 0.1 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 8}}{}$	-	-	80	mA	
		$V_D = 12 \text{ V; } I_G = 0.1 \text{ A; T2- G-;}$ $T_j = 25 \text{ °C; } \frac{\text{Fig. 8}}{}$	-	-	50	mA	
lн	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	40	mA	
V _T	on-state voltage	I _T = 24 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.2	1.5	V	
V _{GT}	gate trigger voltage	V _D = 12 V; T _j = 25 °C; <u>Fig. 11</u>	-	0.7	1	V	
		V _D = 400 V; T _j = 150 °C; <u>Fig. 11</u>	0.2	0.4	-	V	
I _D	off-state current	V _D = 800 V; T _j = 150 °C	-	0.2	1	mA	
Dynamic cl	haracteristics						
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	1250	-	-	V/µs	
dl _{com} /dt	rate of change of commutating current	V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 20 A; dV_{com}/dt = 10 V/µs; gate open circuit	16	-	-	A/ms	
		$V_D = 400 \text{ V}; T_j = 150 \text{ °C}; I_{T(RMS)} = 20 \text{ A};$ $dV_{com}/dt = 1 \text{ V/}\mu\text{s}; \text{ gate open circuit}$	38	-	-	A/ms	

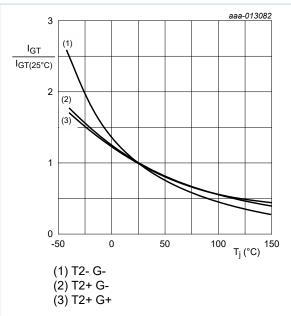


Fig. 7. Normalized gate trigger current as a function of junction temperature

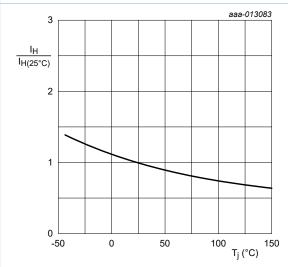


Fig. 9. Normalized holding current as a function of junction temperature

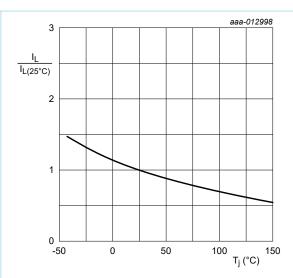
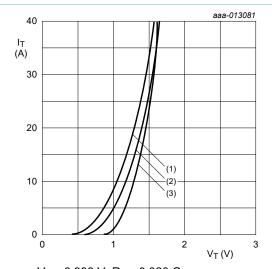


Fig. 8. Normalized latching current as a function of junction temperature



 V_o = 0.998 V; R_s = 0.020 Ω (1) T_j = 150 °C; typical values (2) T_j = 150 °C; maximum values (3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

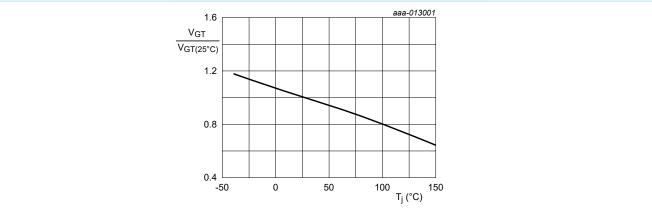
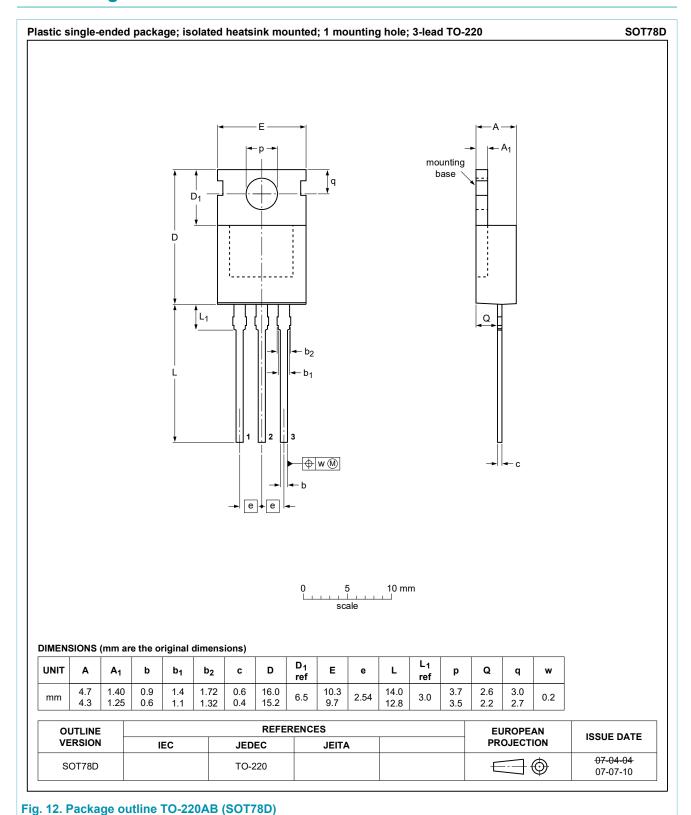


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline



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12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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